

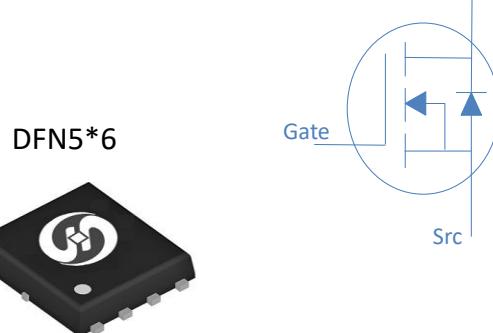
**30V N-Ch Power MOSFET**
**Feature**

- ◊ High Speed Power Switching
- ◊ Enhanced Body diode dv/dt capability
- ◊ Enhanced Avalanche Ruggedness
- ◊ 100% UIS Tested, 100% Rg Tested
- ◊ Lead Free, Halogen Free

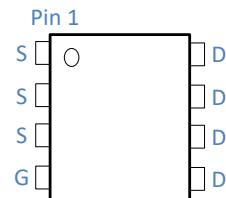
$V_{DS}$	30	V
$R_{DS(on),typ}$	0.55	$m\Omega$
$I_D$ (Silicon Limited)	343	A
$I_D$ (Package Limited)	100	A

**Application**

- ◊ Synchronous Rectification in SMPS
- ◊ Hard Switching and High Speed Circuit
- ◊ DC/DC in Telecoms and Industrial



Part Number	Package	Marking
HGN006N03A	DFN5*6	GN006N03A


**Absolute Maximum Ratings at  $T_j=25^\circ C$  (unless otherwise specified)**

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current(Silicon Limited)	$I_D$	$T_C=25^\circ C$	343	A
Continuous Drain Current(Package Limited)		$T_C=100^\circ C$	217	
Continuous Drain Current		$T_C=25^\circ C$	100	
Drain to Source Voltage	$V_{DS}$	-	30	V
Gate to Source Voltage	$V_{GS}$	-	$\pm 20$	V
Pulsed Drain Current	$I_{DM}$	-	1000	A
Avalanche Energy, Single Pulse	$E_{AS}$	$L=0.1mH, T_C=25^\circ C$	180	mJ
Power Dissipation	$P_D$	$T_C=25^\circ C$	119	W
Operating and Storage Temperature	$T_J, T_{stg}$	-	-55 to 150	°C

**Absolute Maximum Ratings**

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Ambient	$R_{\theta JA}$	55	°C/W
Thermal Resistance Junction-Case	$R_{\theta JC}$	1.05	°C/W

**Electrical Characteristics at  $T_j=25^\circ\text{C}$  (unless otherwise specified)**
**Static Characteristics**

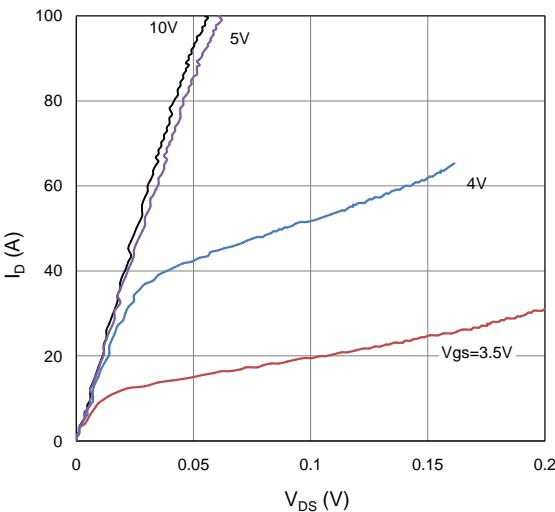
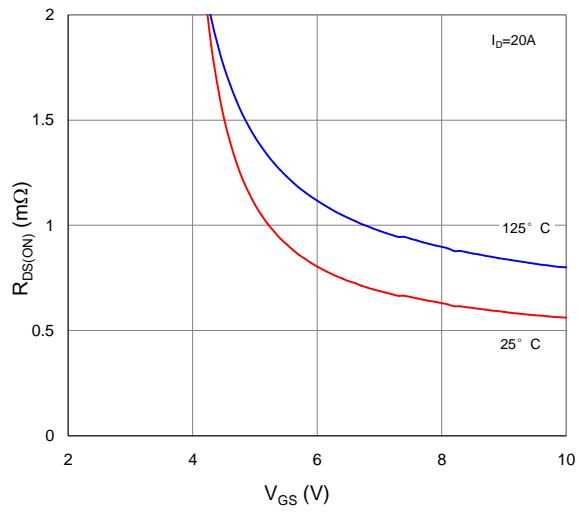
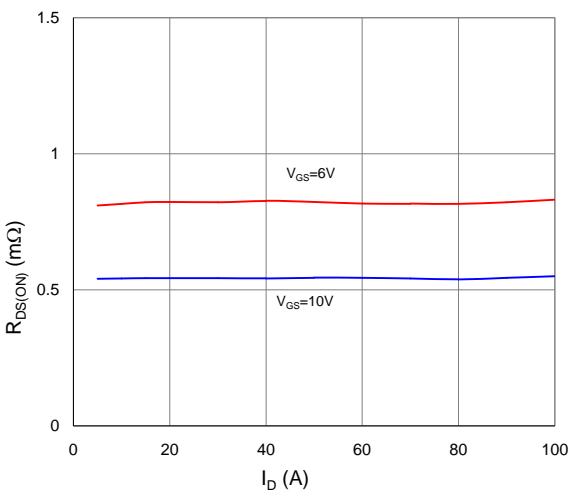
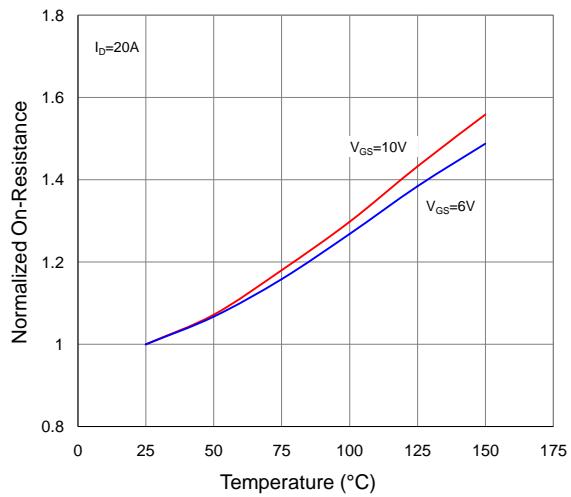
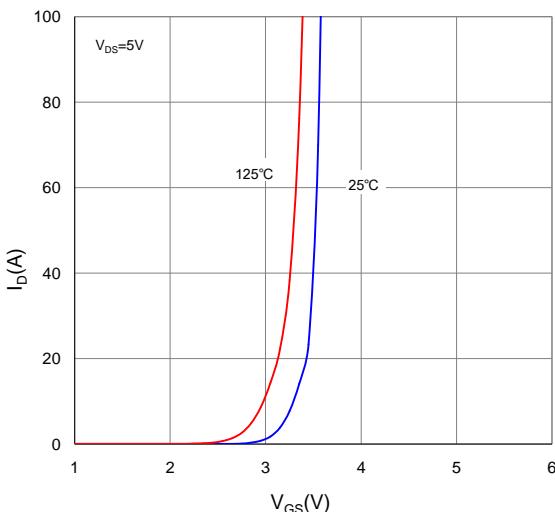
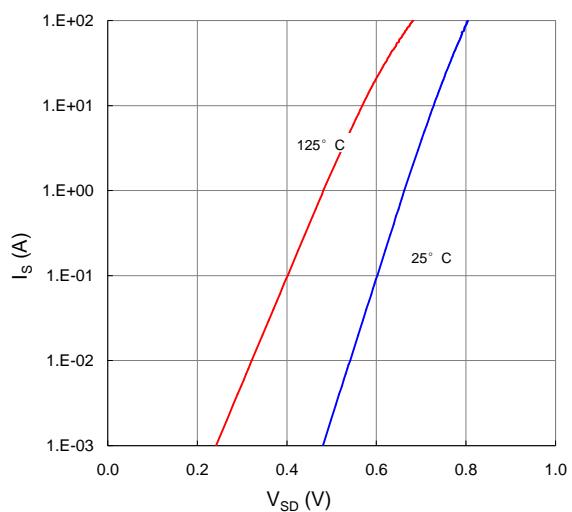
Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	30	-	-	V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_D=250\mu\text{A}$	2	2.3	4	
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=30\text{V}, T_j=25^\circ\text{C}$	-	-	1	$\mu\text{A}$
		$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=30\text{V}, T_j=100^\circ\text{C}$	-	-	100	
Gate to Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
Drain to Source on Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_D=20\text{A}$	-	0.55	0.65	$\text{m}\Omega$
Transconductance	$g_{\text{fs}}$	$V_{\text{DS}}=5\text{V}, I_D=20\text{A}$	-	85	-	S
Gate Resistance	$R_G$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}} \text{ Open}, f=1\text{MHz}$	-	0.95	-	$\Omega$

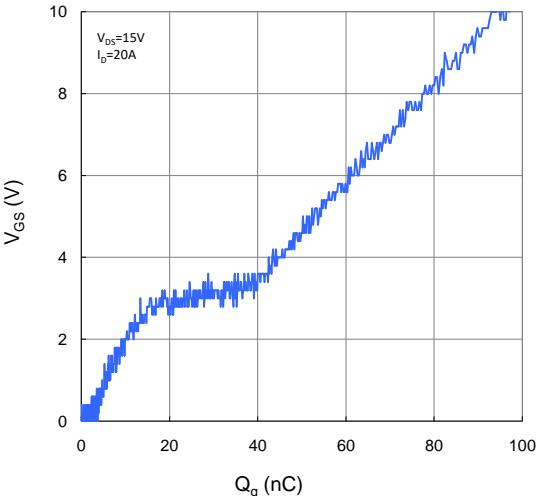
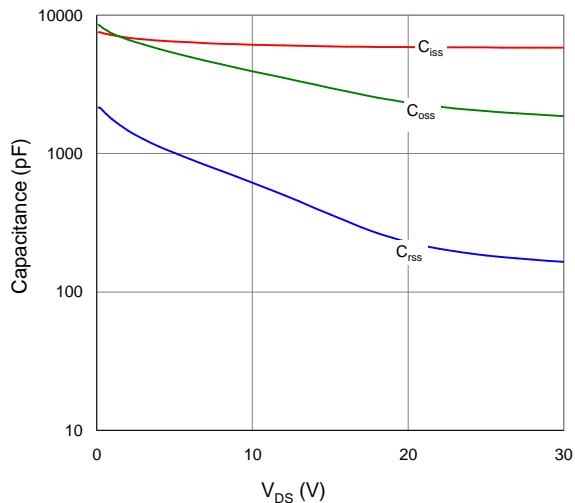
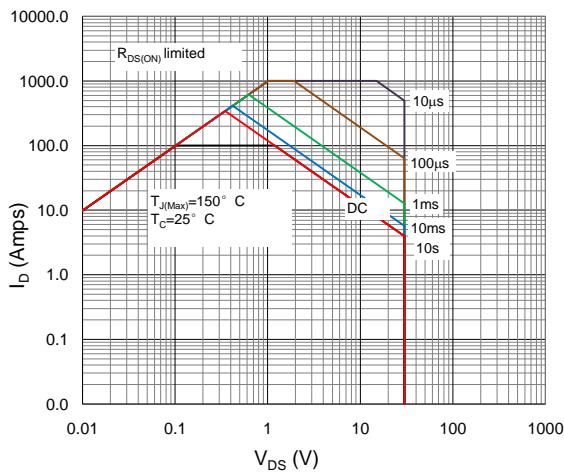
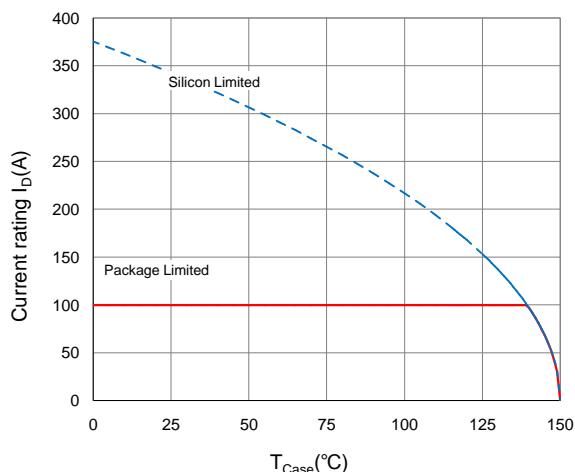
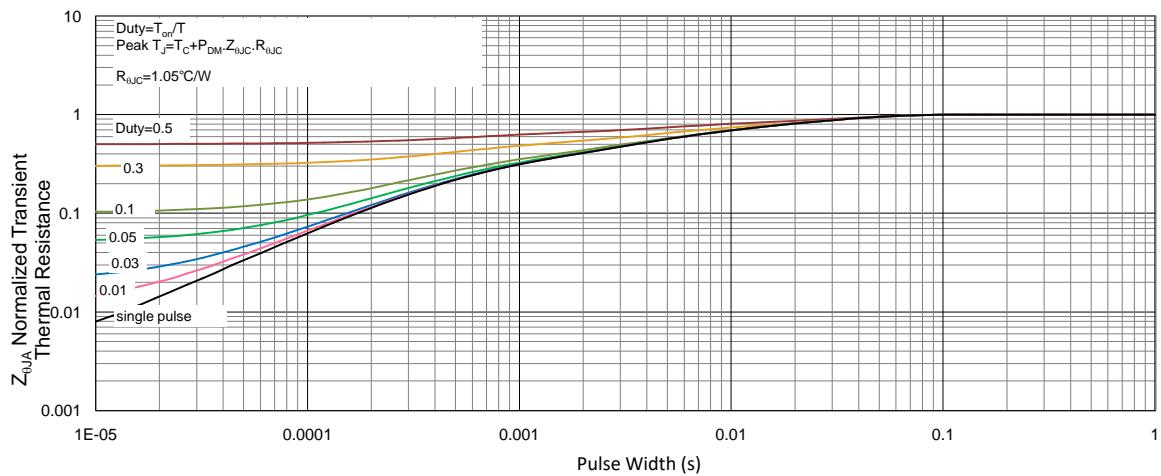
**Dynamic Characteristics**

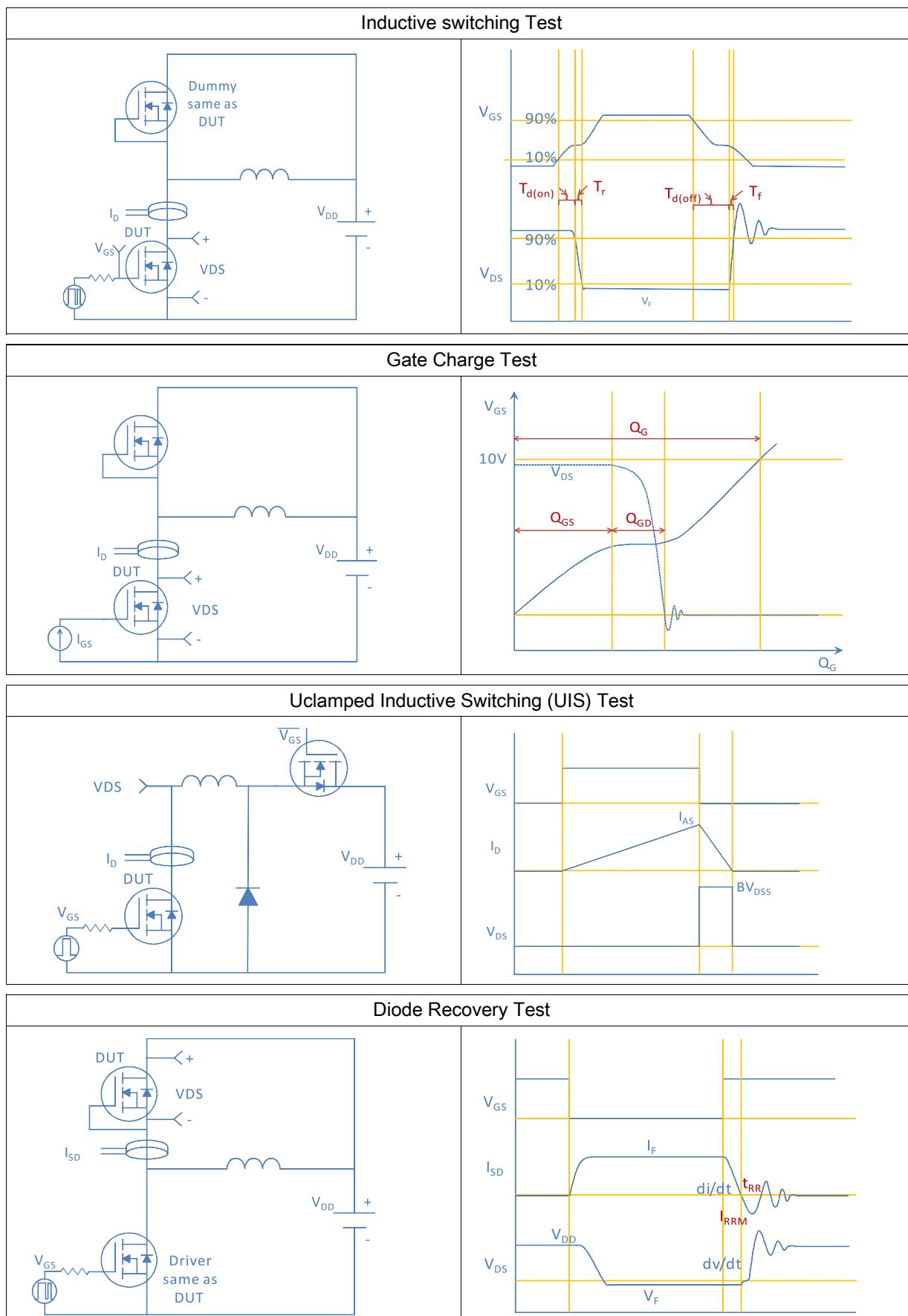
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=15\text{V}, f=1\text{MHz}$	-	5948	-	pF
Output Capacitance	$C_{\text{oss}}$		-	2978	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	363	-	
Total Gate Charge	$Q_g(10\text{V})$	$V_{\text{DD}}=15\text{V}, I_D=20\text{A}, V_{\text{GS}}=10\text{V}$	-	93	-	nC
Gate to Source Charge	$Q_{\text{gs}}$		-	14	-	
Gate to Drain (Miller) Charge	$Q_{\text{gd}}$		-	26	-	
Turn on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=15\text{V}, I_D=20\text{A}, V_{\text{GS}}=10\text{V}$	-	20	-	ns
Rise time	$t_r$		-	13	-	
Turn off Delay Time	$t_{\text{d}(\text{off})}$		-	37	-	
Fall Time	$t_f$		-	9	-	

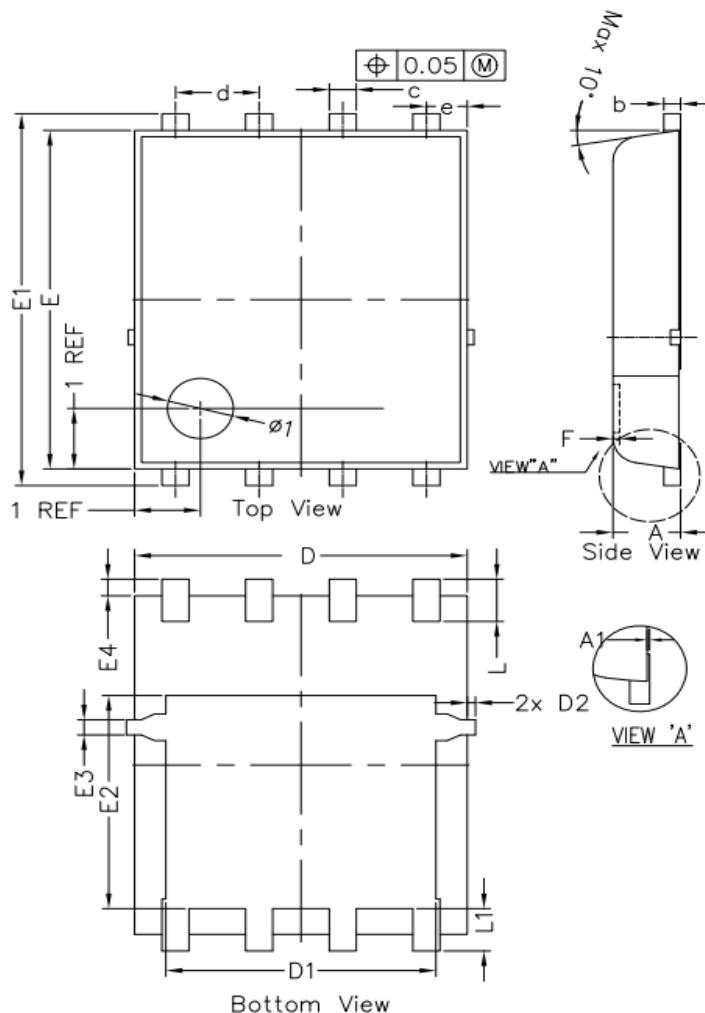
**Reverse Diode Characteristics**

Diode Forward Voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_F=100\text{A}$	-	0.8	1.2	V
Reverse Recovery Time	$t_{\text{rr}}$	$V_R=15\text{V}, I_F=20\text{A}, dI_F/dt=100\text{A}/\mu\text{s}$	-	62	-	ns
Reverse Recovery Charge	$Q_{\text{rr}}$		-	68	-	nC

**Fig 1. Typical Output Characteristics**

**Figure 2. On-Resistance vs. Gate-Source Voltage**

**Figure 3. On-Resistance vs. Drain Current and Gate Voltage**

**Figure 4. Normalized On-Resistance vs. Junction Temperature**

**Figure 5. Typical Transfer Characteristics**

**Figure 6. Typical Source-Drain Diode Forward Voltage**


**Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage**

**Figure 8. Typical Capacitance vs. Drain-to-Source Voltage**

**Figure 9. Maximum Safe Operating Area**

**Figure 10. Maximum Drain Current vs. Case Temperature**

**Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Ambient**




**Package Outline**
**DFN5\*6, 8 leads**


SYMBOLS	DIMENSION IN MM			DIMENSION IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
* A	0.900	1.000	1.100	0.035	0.039	0.043
A1	0.000	---	0.050	0.000	----	0.002
b	0.246	0.254	0.312	0.010	0.010	0.012
* c	0.310	0.410	0.510	0.012	0.016	0.020
d	1.27 BSC			0.050 BSC		
* D	4.950	5.050	5.150	0.195	0.199	0.203
D1	4.000	4.100	4.200	0.157	0.161	0.165
* D2	---	---	0.125	---	---	0.005
e	0.62 BSC			0.024 BSC		
* E	5.500	5.600	5.700	0.217	0.220	0.224
* E1	6.050	6.150	6.250	0.238	0.242	0.246
E2	3.425	3.525	3.625	0.135	0.139	0.143
E3	0.150	0.250	0.350	0.006	0.010	0.014
* E4	0.175	0.275	0.375	0.007	0.011	0.015
F	-	-	0.100	-	-	0.004
* L	0.500	0.600	0.700	0.02	0.02	0.03
L1	0.600	0.700	0.800	0.02	0.03	0.03